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Product Change	Notification - JAON	-20TV	FV764	(Printer F	riendly)											
Date:	27 Nov 2015															
Notification subject:	CCB 1787 Initial Notice C7025 lead frame, CRM						evice fa	imilies i	n 128L	. TQFF	, packa	ge usir	ng CuF	PdAu w	ire,	
Notification text:	PCN Status: Initial notification															
	Microchip Parts Afference Please open the attack		found in	the attachm	ents field	below label	ed as	PCN_	#_Affe	cted_	CPN.					
	NOTE: For your conv	enience	Microchi	ip includes i	lentical fi	les in two foi	rmats	(.pdf a	nd .xls	s).						
	Description of Chan Qualification of ASE a coated copper with gold material.	assembly													lladium	
	Pre Change: Assembled at ATT as material	Assembled at ATT assembly site using Gold (Au) bond wire, C194 lead frame, 3230 die attach and G700L molding compound														
	Post Change: Assembled at ASE as die attach and G631F Pre and Post Chang	1 molding	g compoi			per with gold t	flash (C	CuPdAu	ı) bond	wire,	C7025	lead f	rame	, CRM	-1076	
						Pre Ch	ange				P	Post C	hang	e		
	Ass	sembly S	Site			Pre Ch	•	ite				Post C				
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Qual Report

Implementation

Availability Final PCN Issue

Date

Date

Markings to Distinguish Revised from Unrevised Devices: Traceability code

Revision History: November 27, 2015: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_JAON-20TVFV764_Qual_Plan.pdf PCN_JAON-20TVFV764_Affected_CPN.pdf PCN_JAON-20TVFV764_Affected_CPN.xls

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